



FIG. 1
PRIOR ART

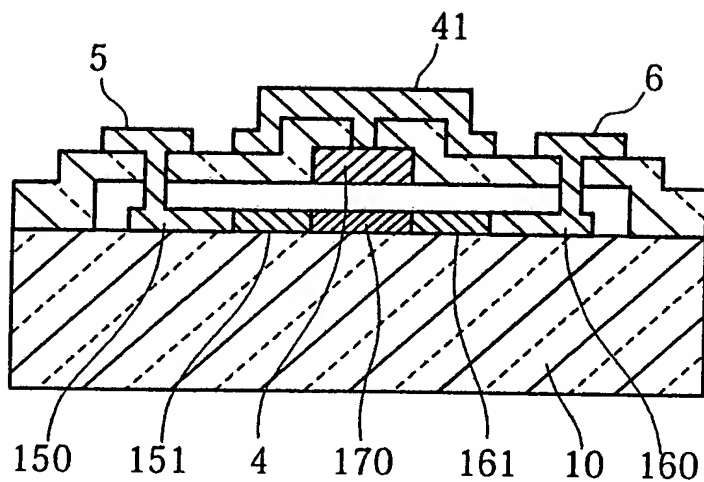


FIG. 2
PRIOR ART

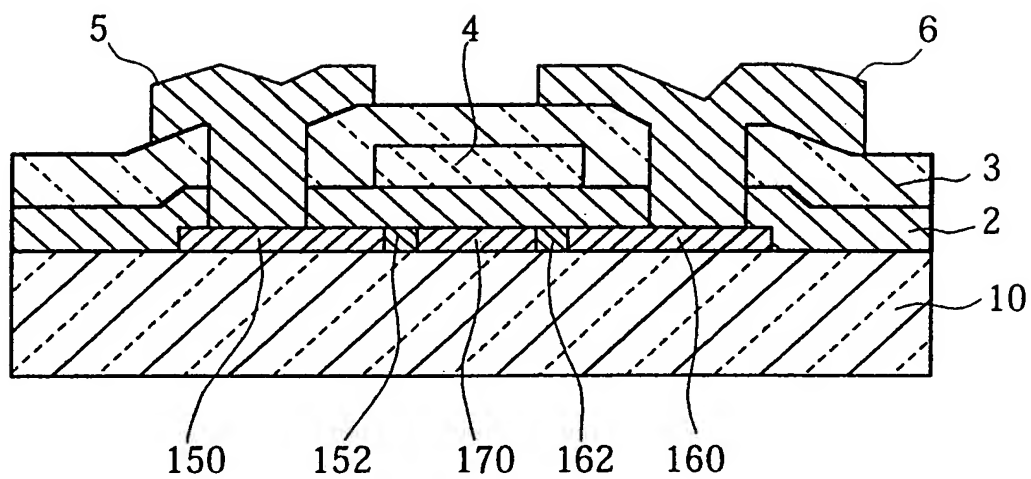


FIG. 3

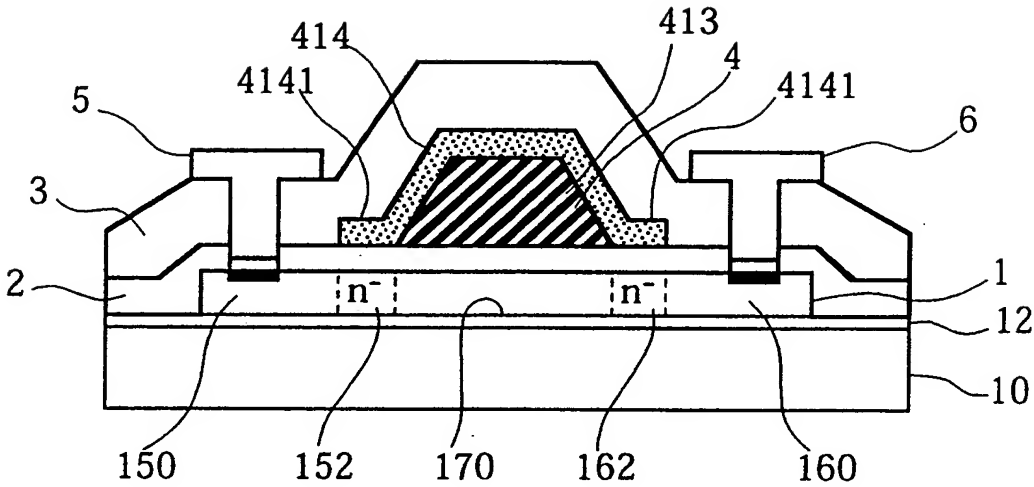


FIG. 4

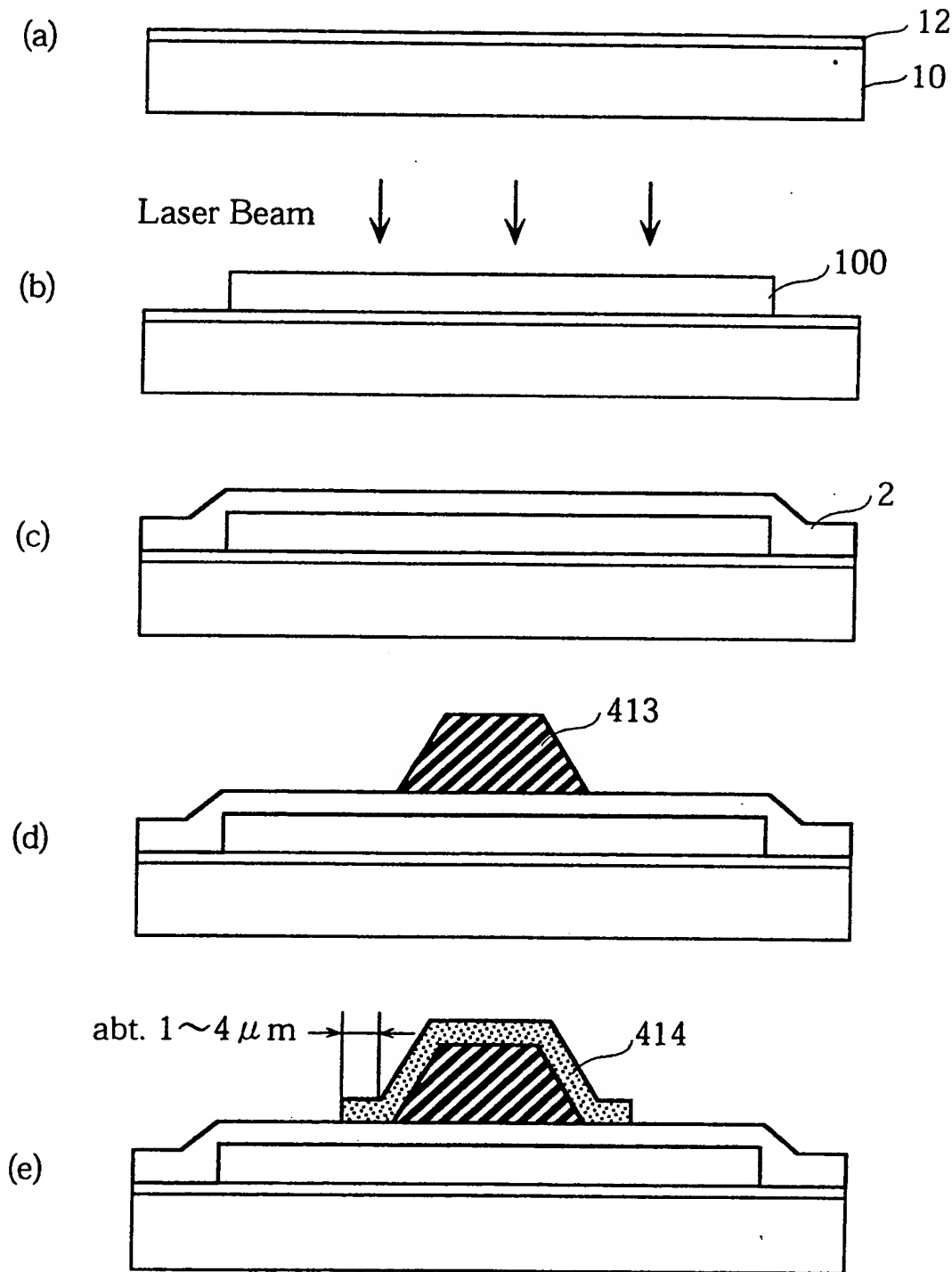


FIG. 5

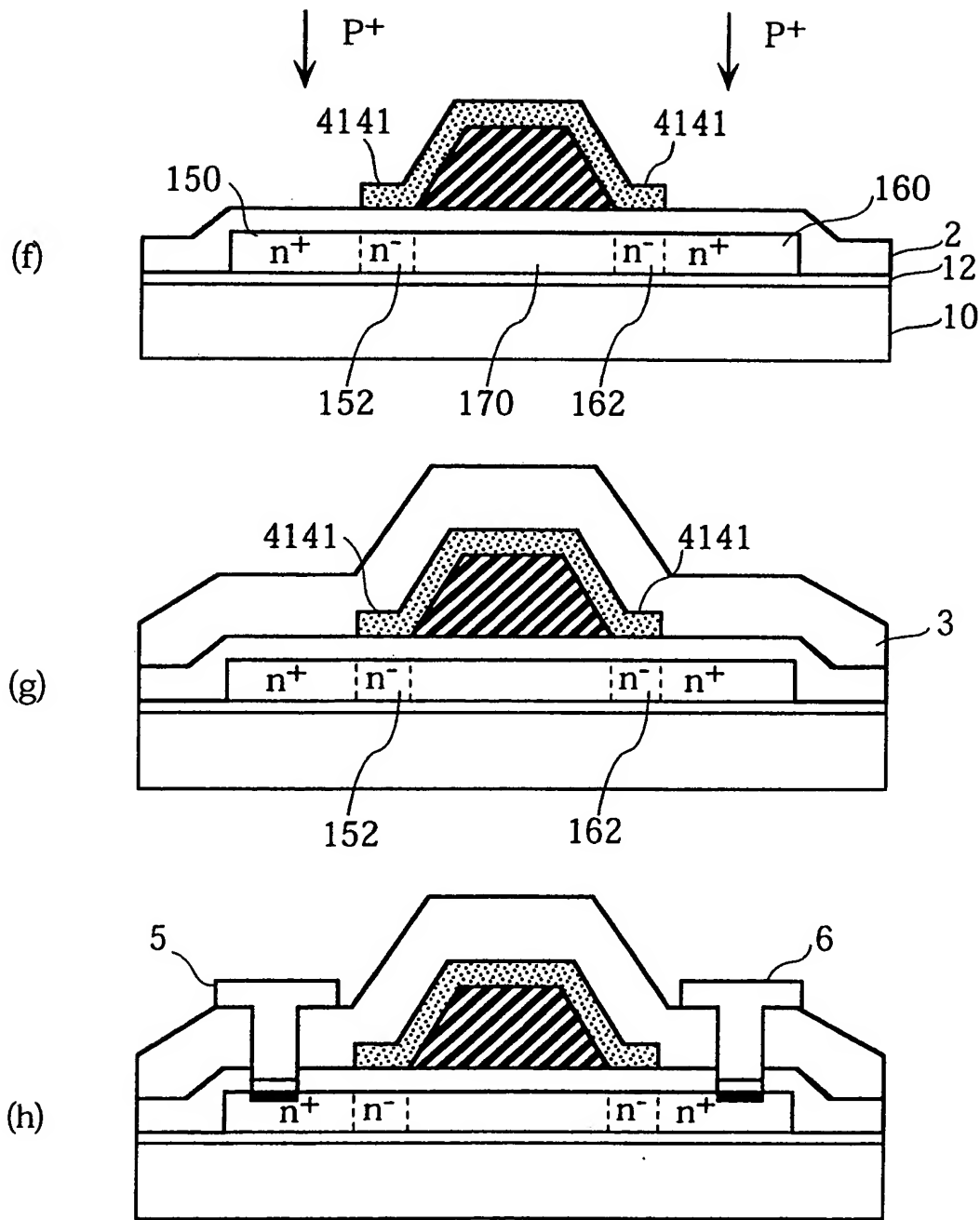


FIG. 6

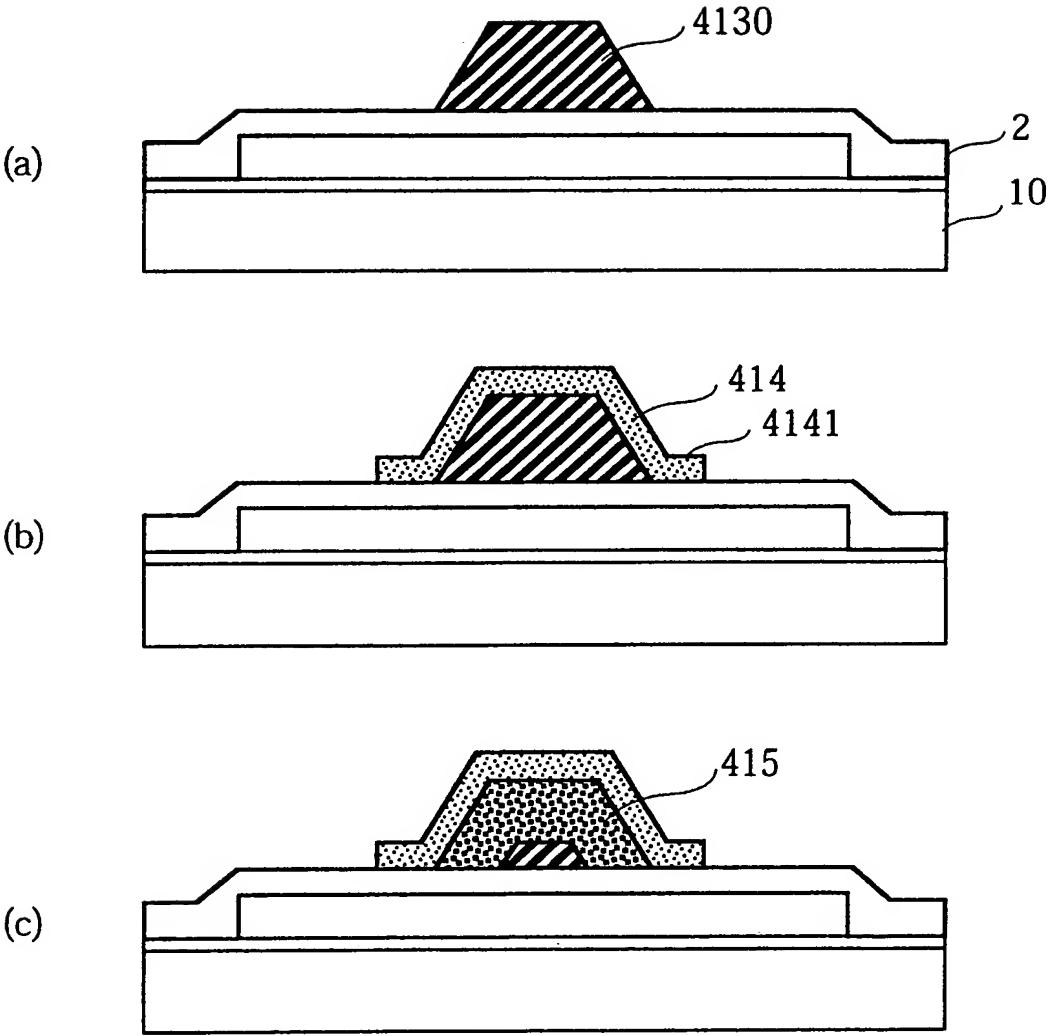


FIG. 7

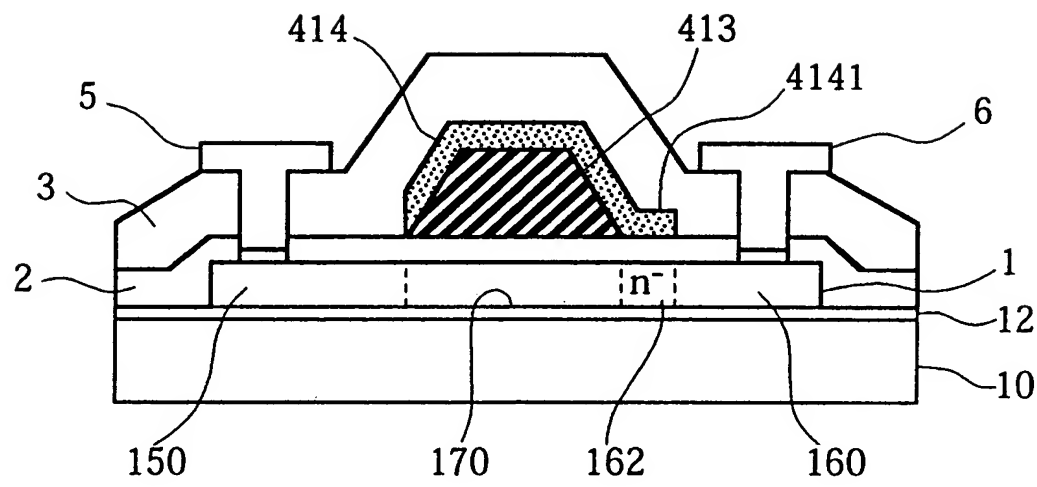


FIG. 8

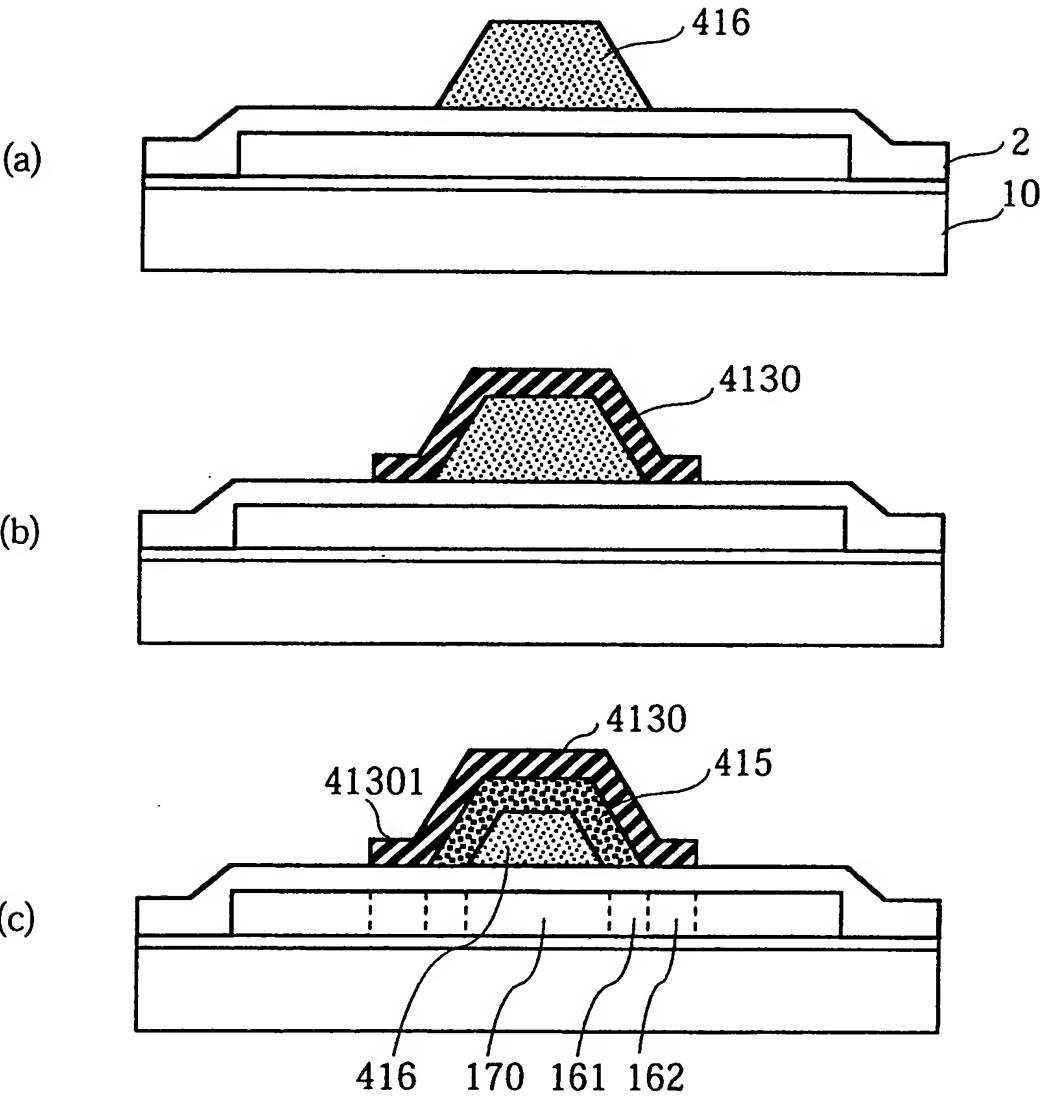


FIG. 9

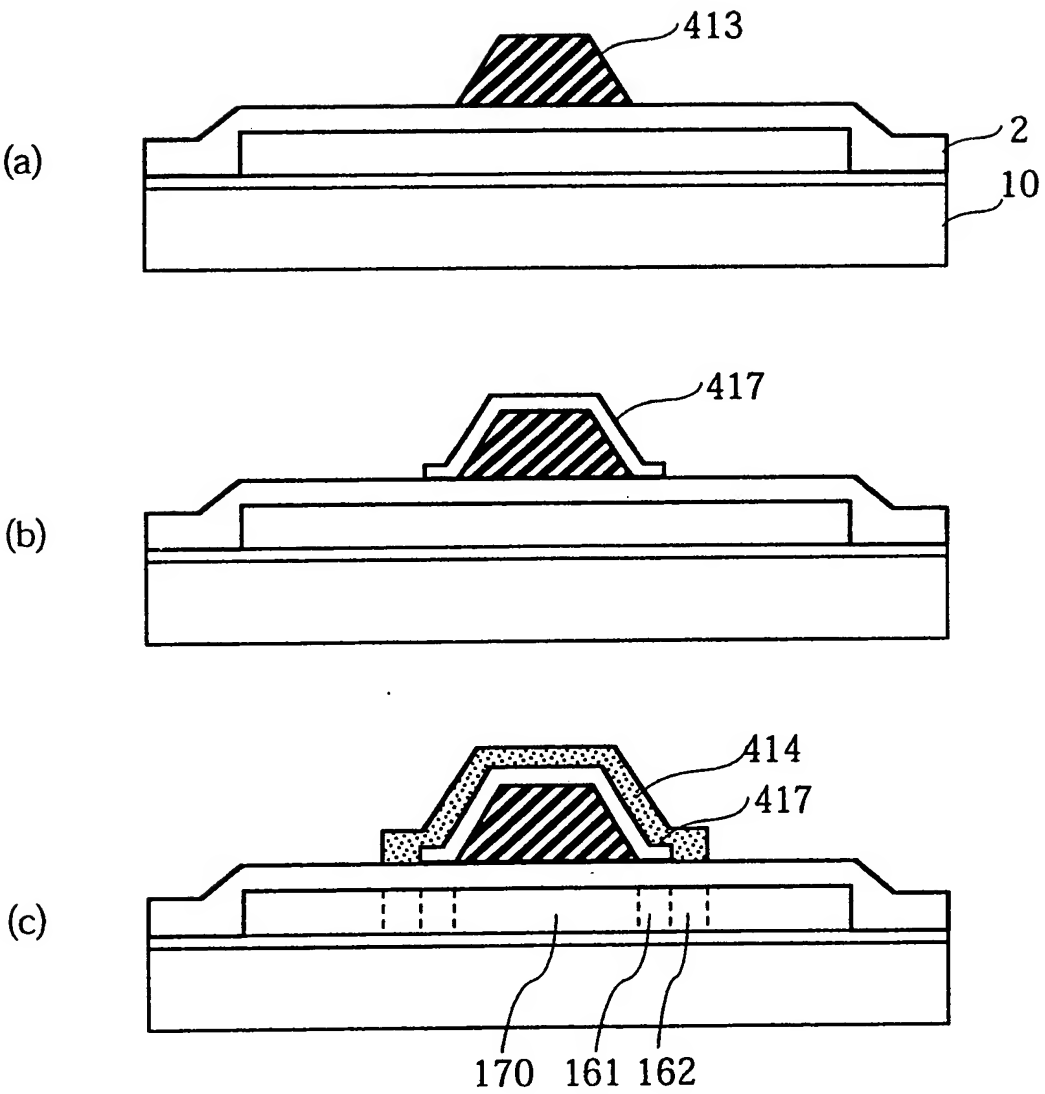


FIG. 10

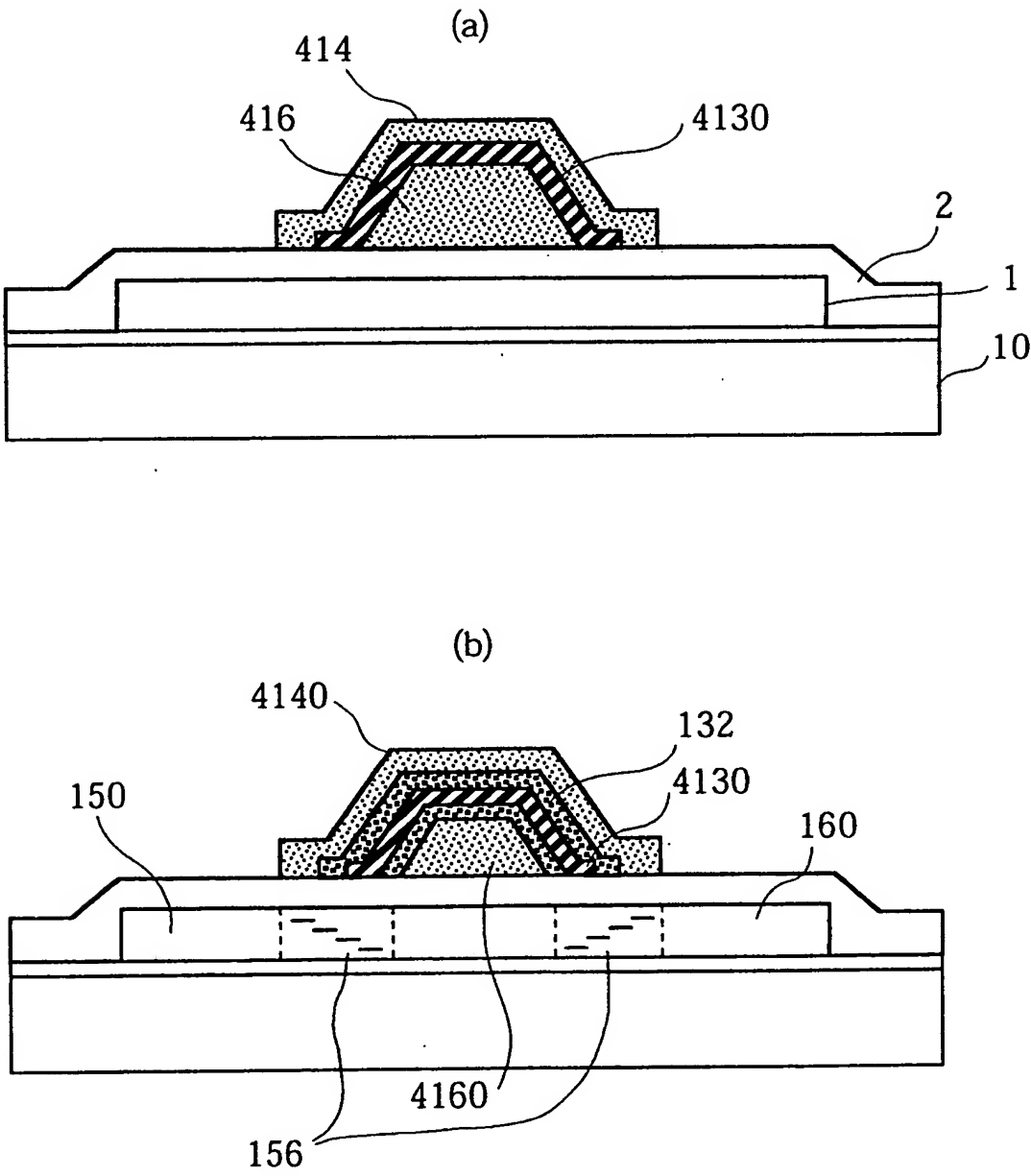


FIG. 11

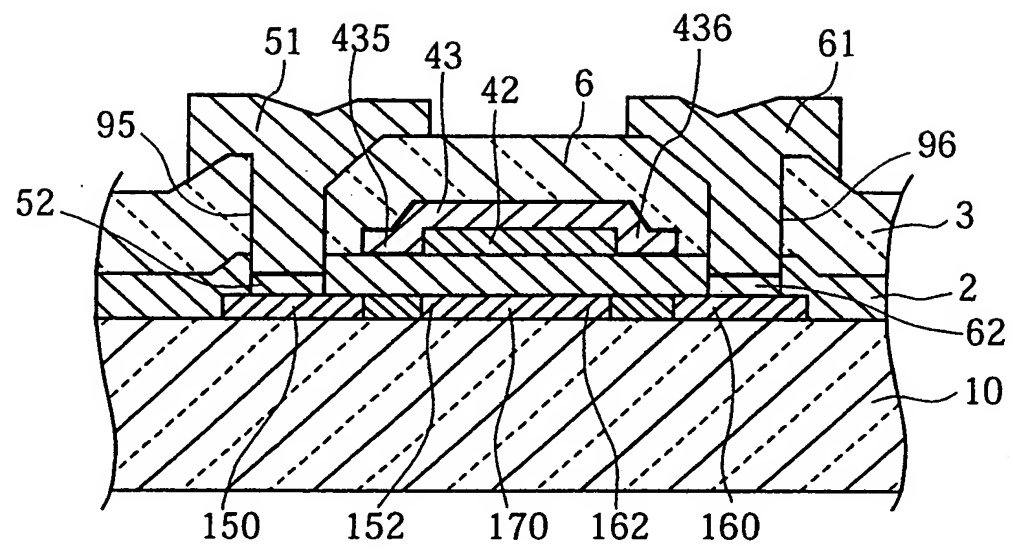


FIG. 12

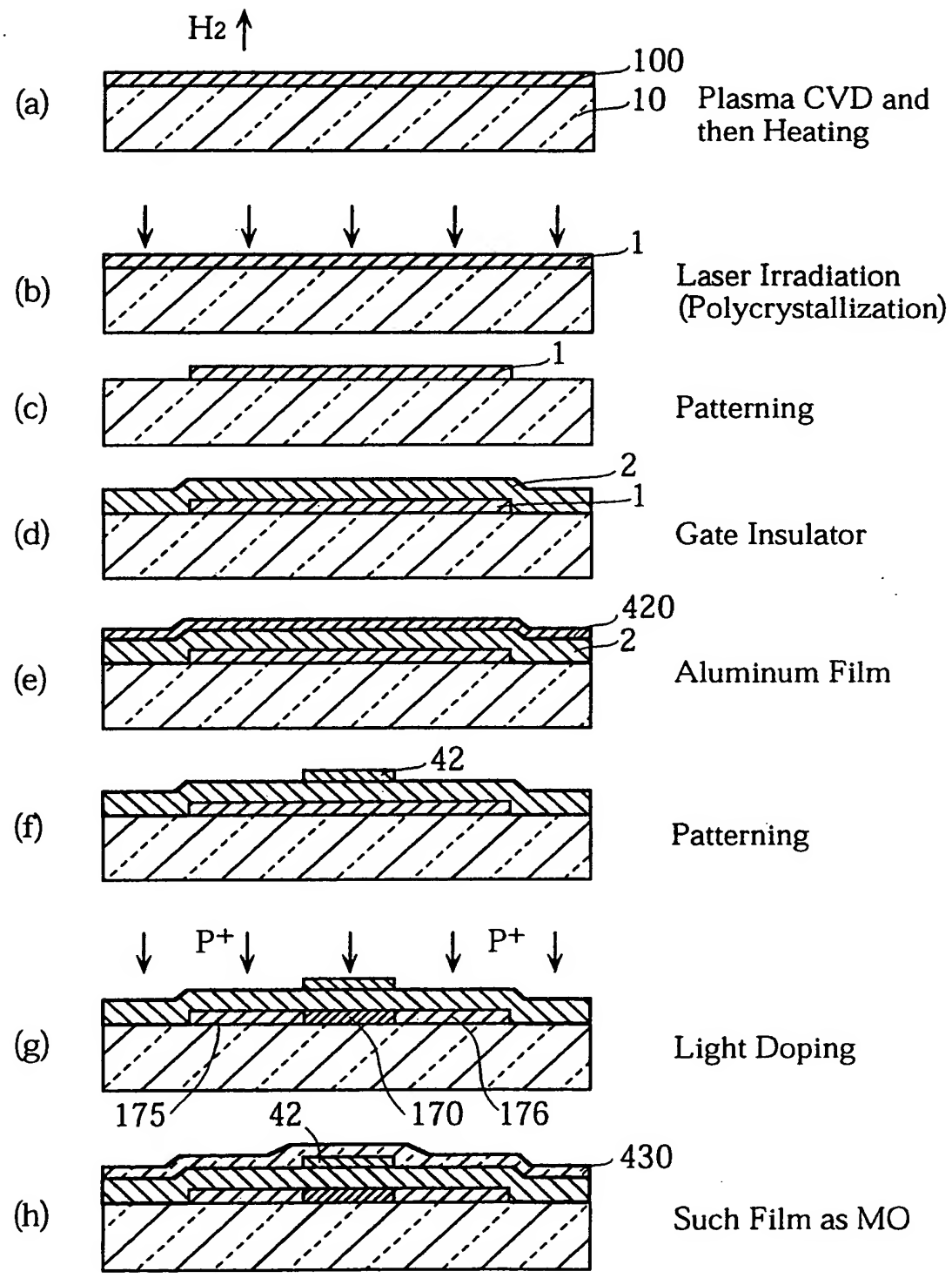


FIG. 13

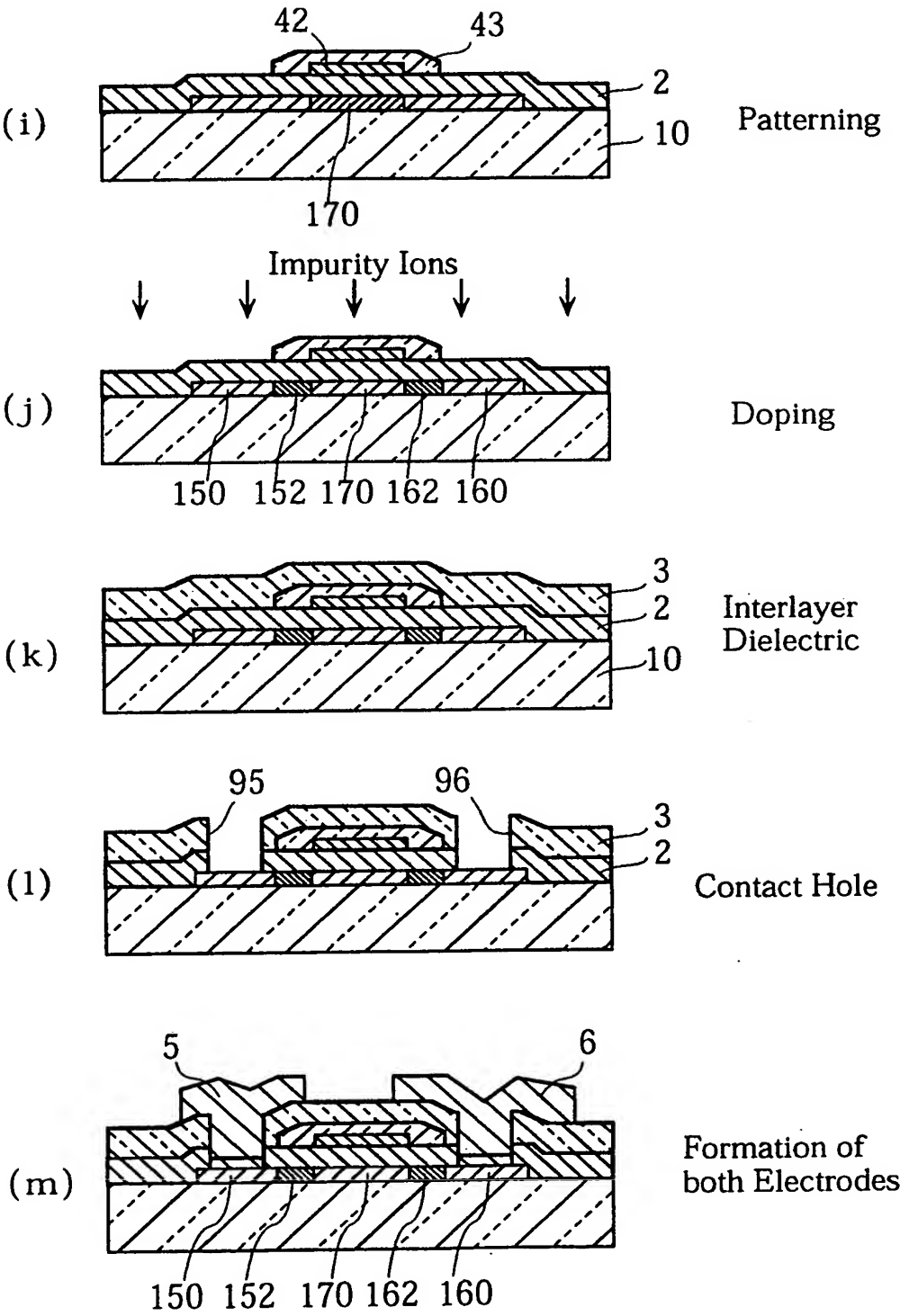


FIG. 14

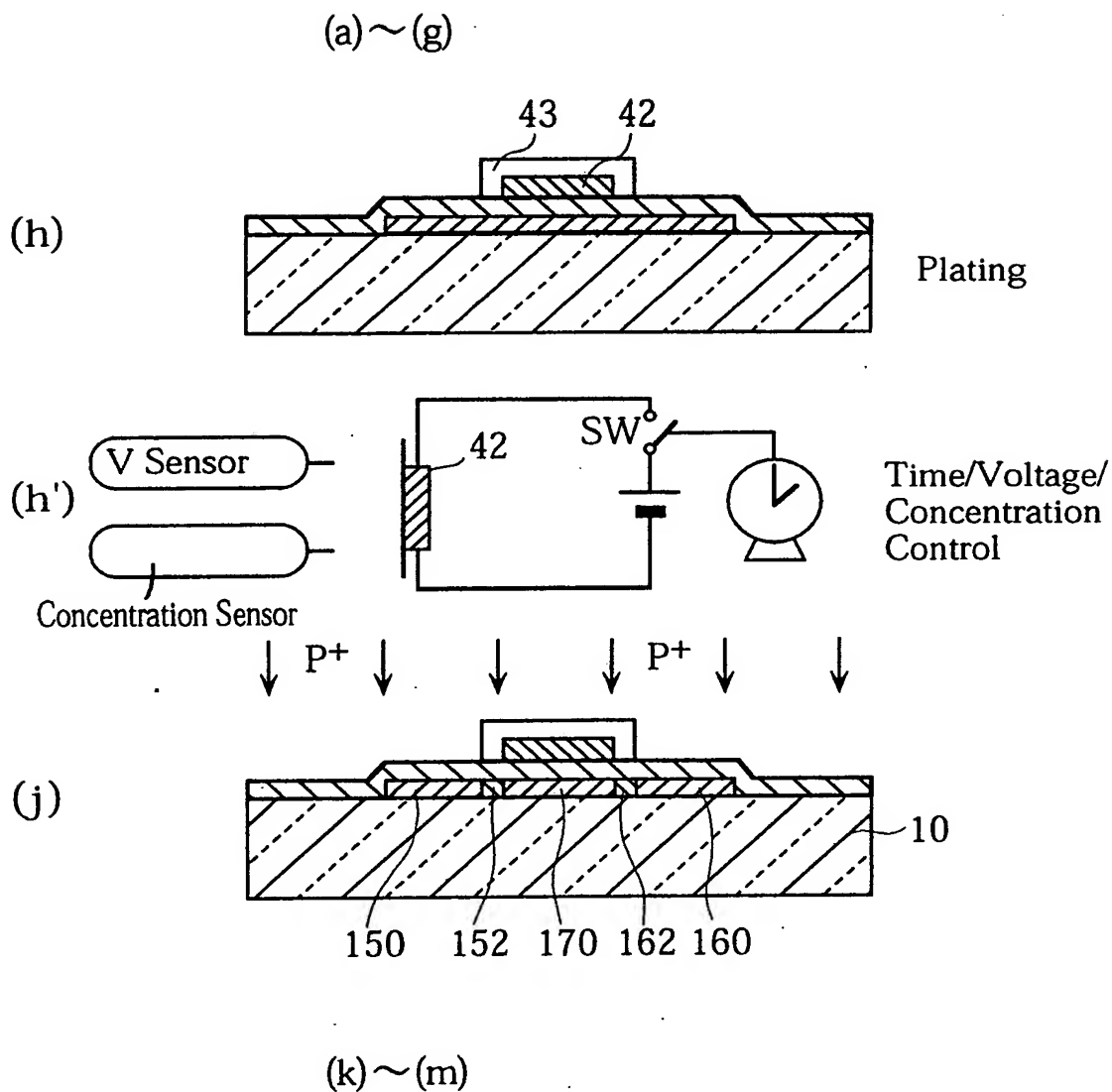


FIG. 15

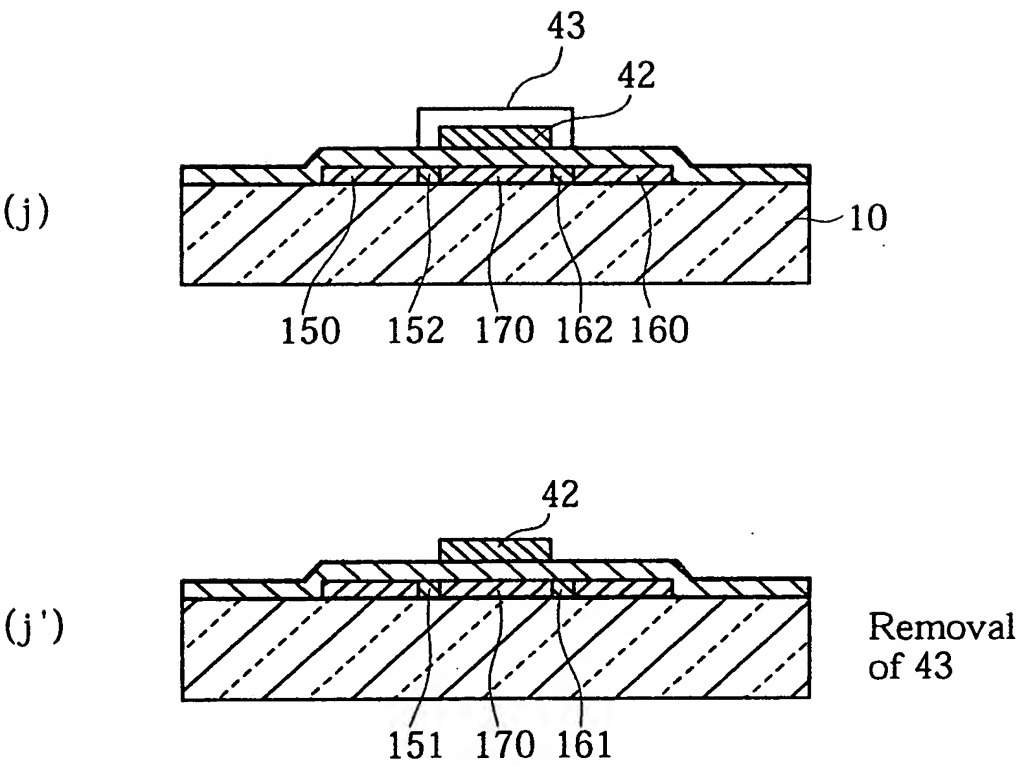


FIG. 16

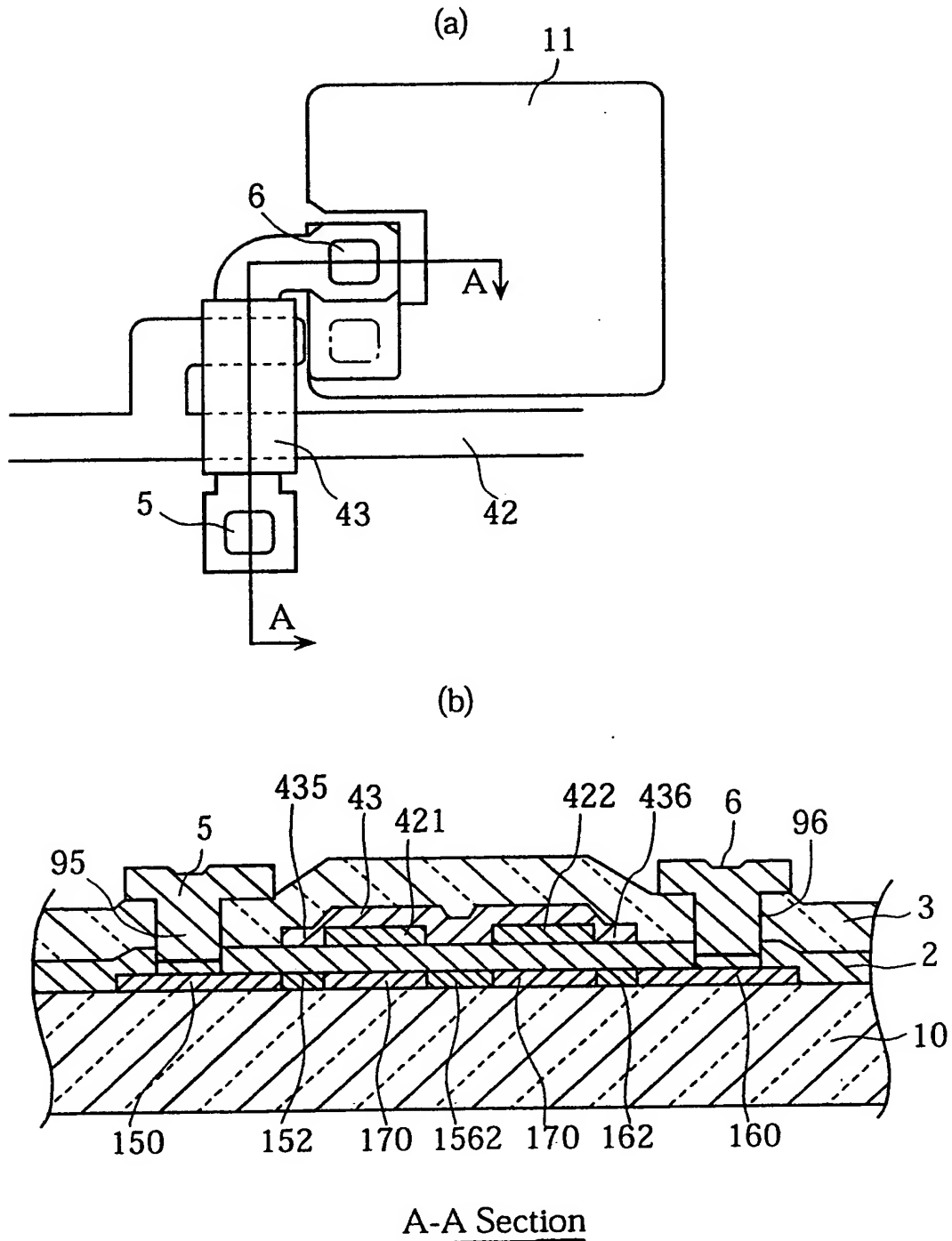


FIG. 17

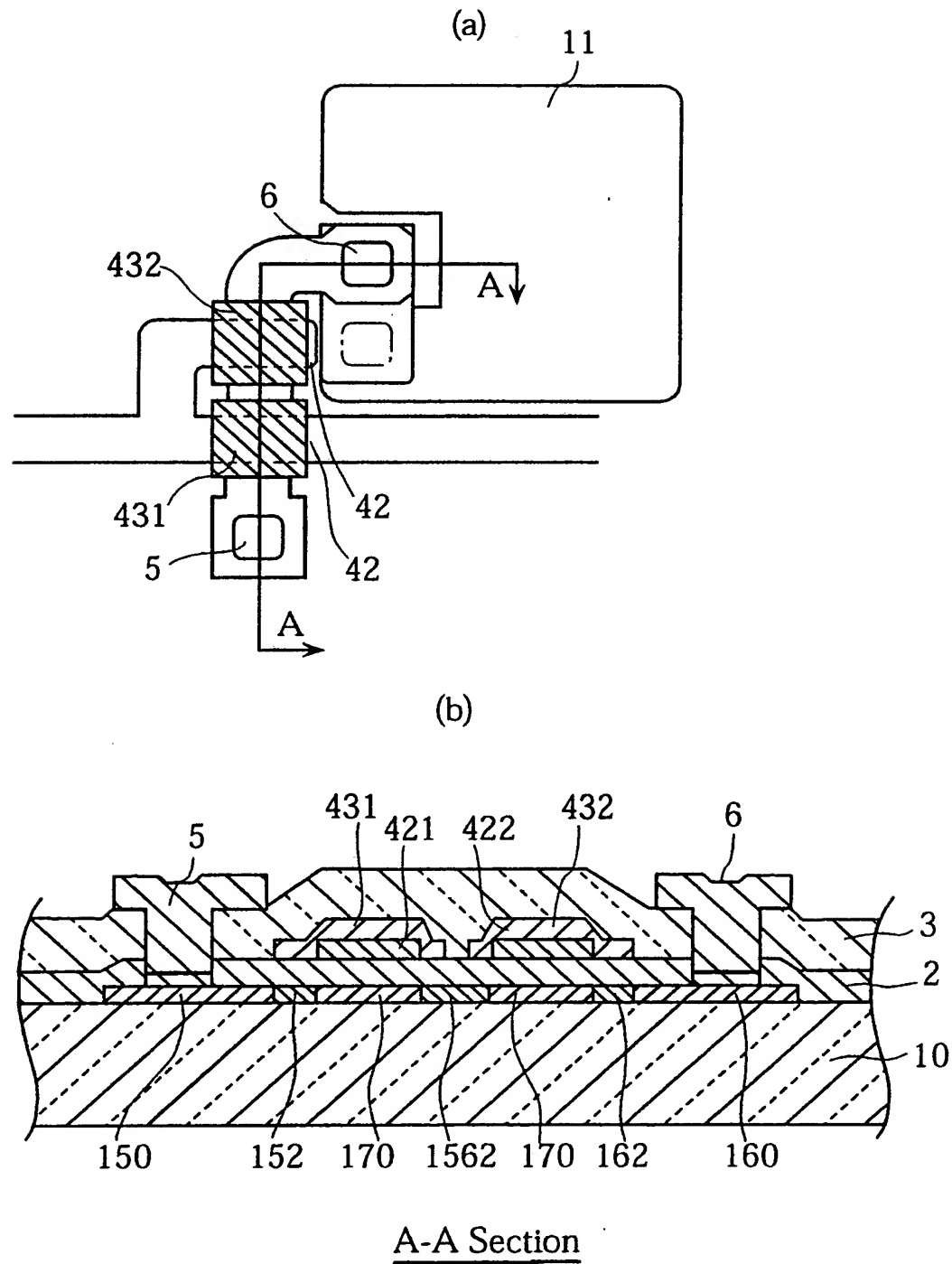


FIG. 18

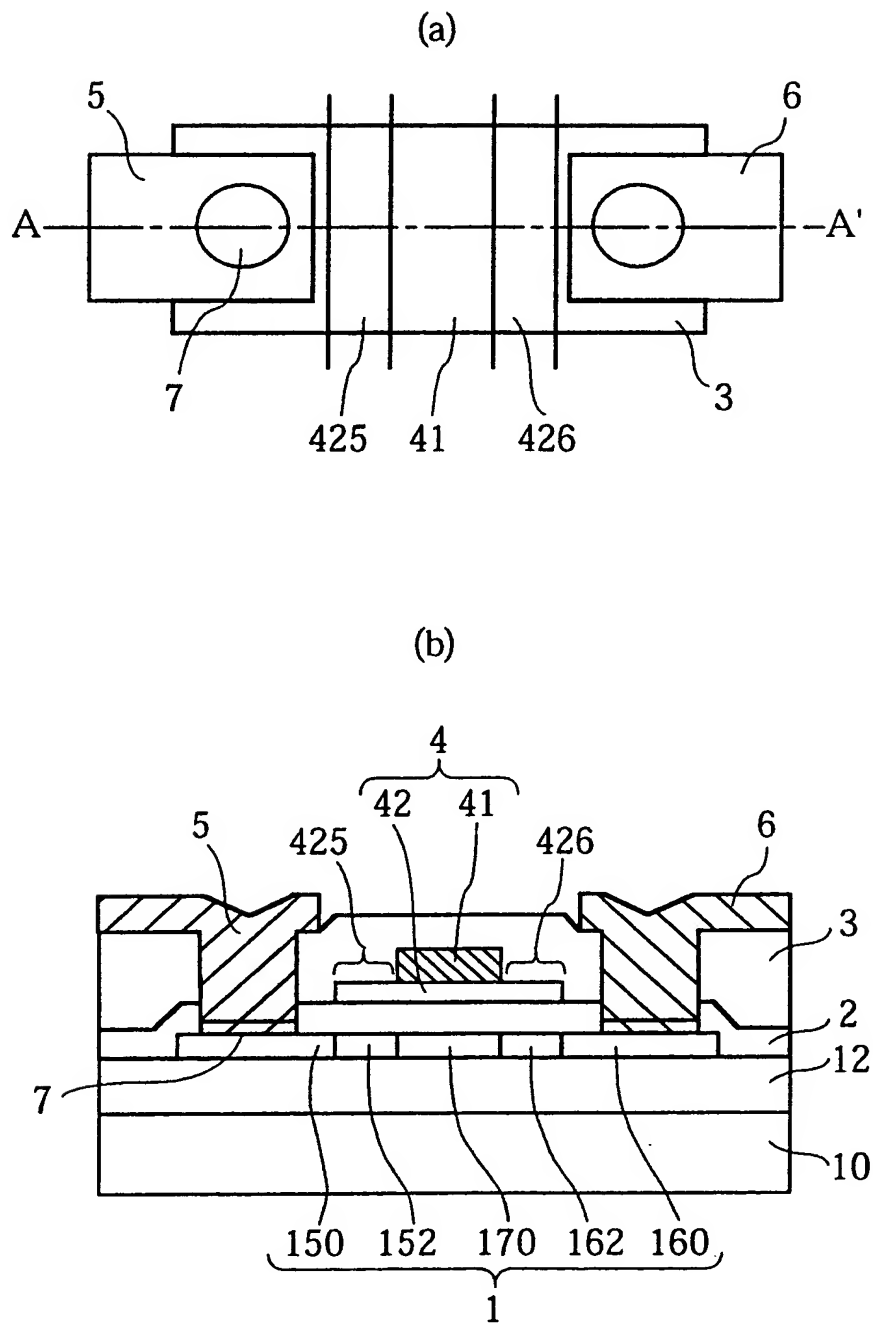


FIG. 19

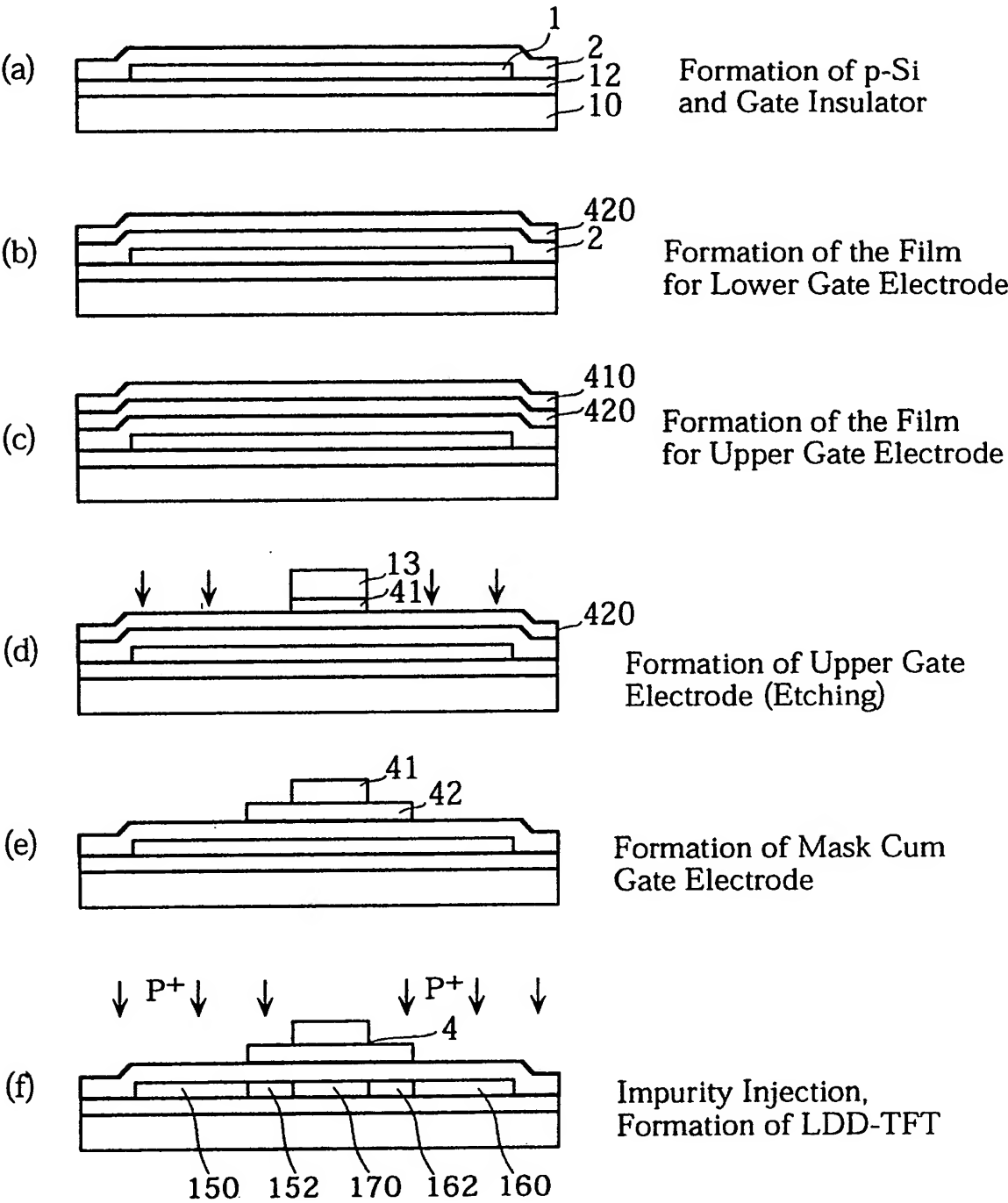


FIG. 20

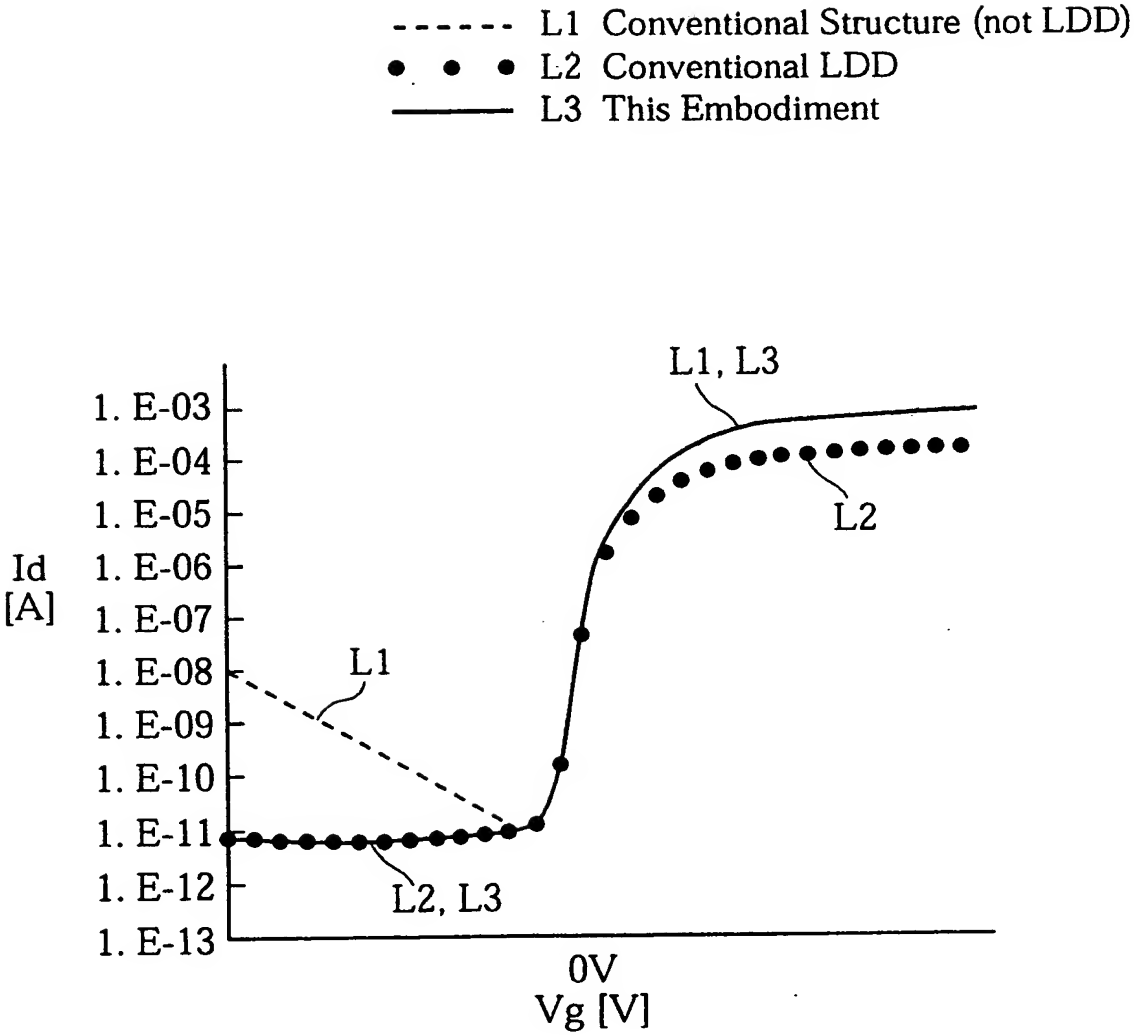


FIG. 21

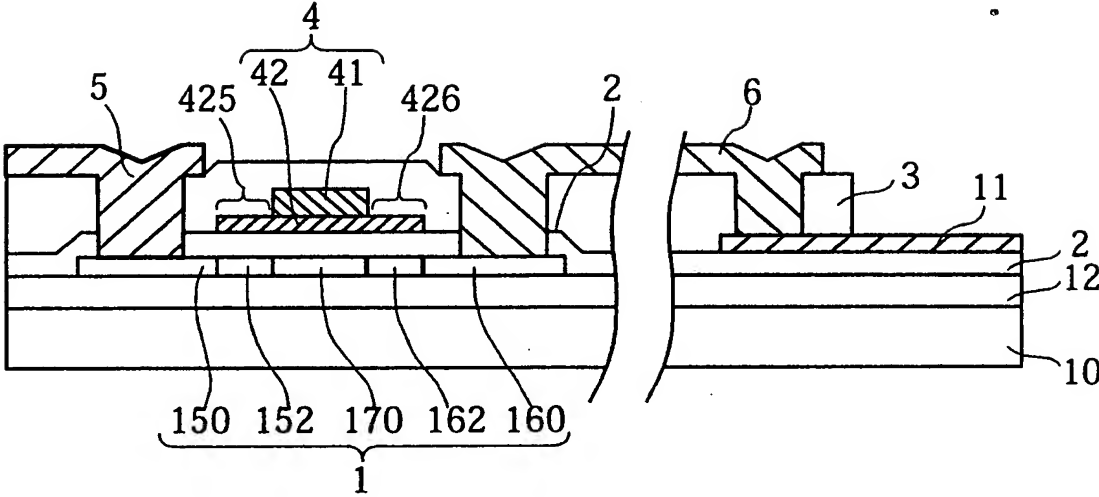


FIG. 22

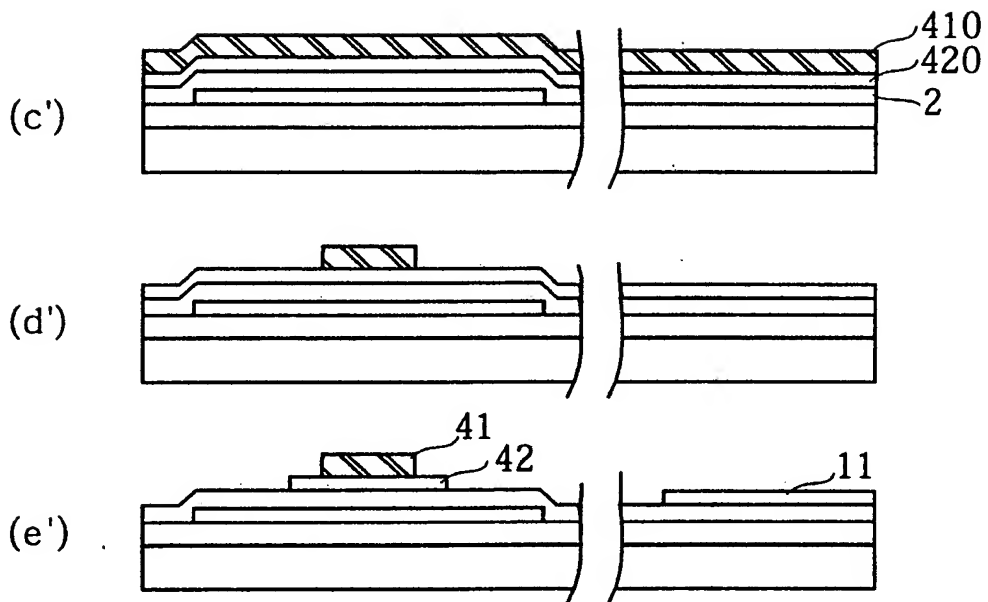


FIG. 23

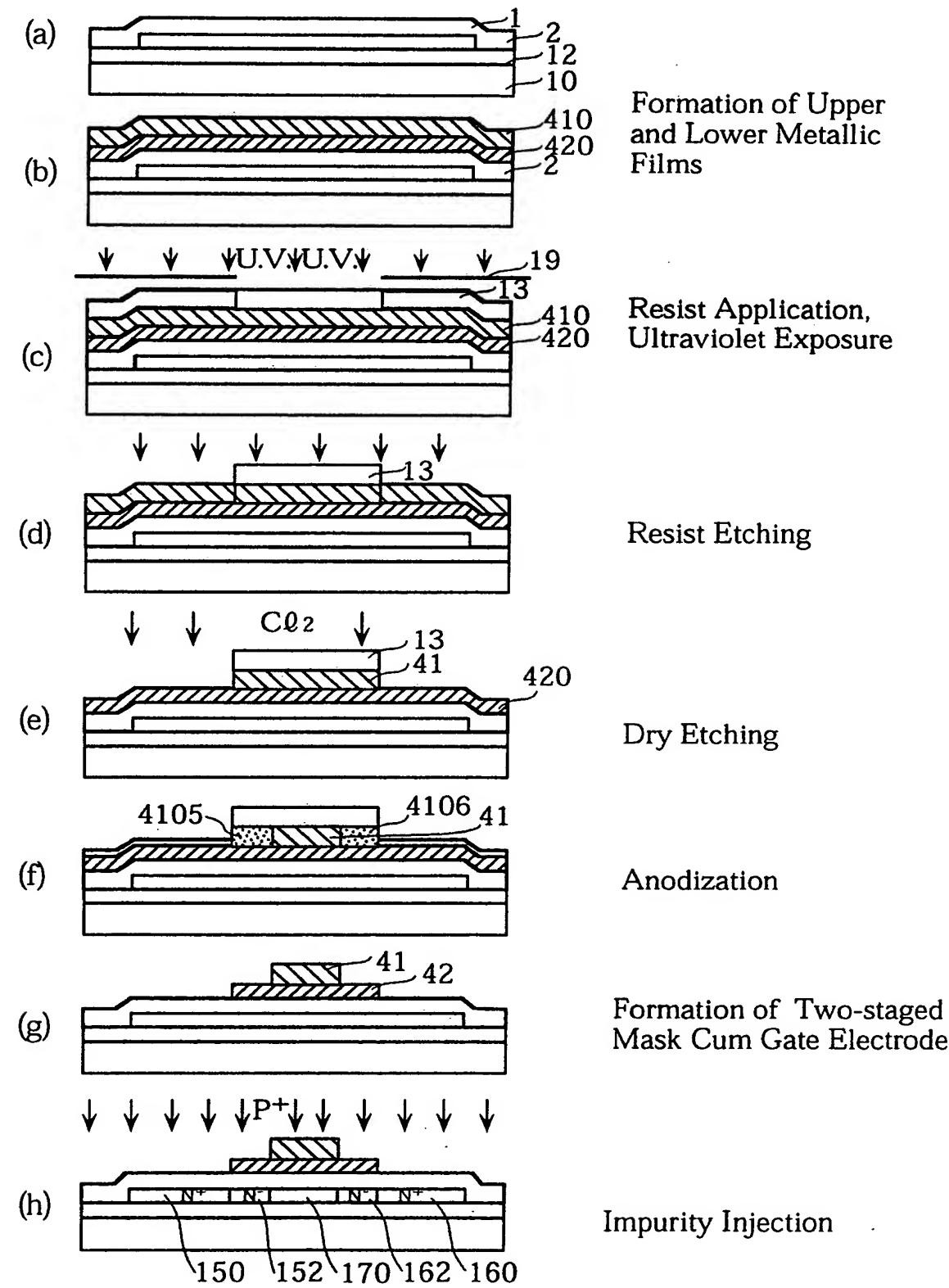


FIG. 24

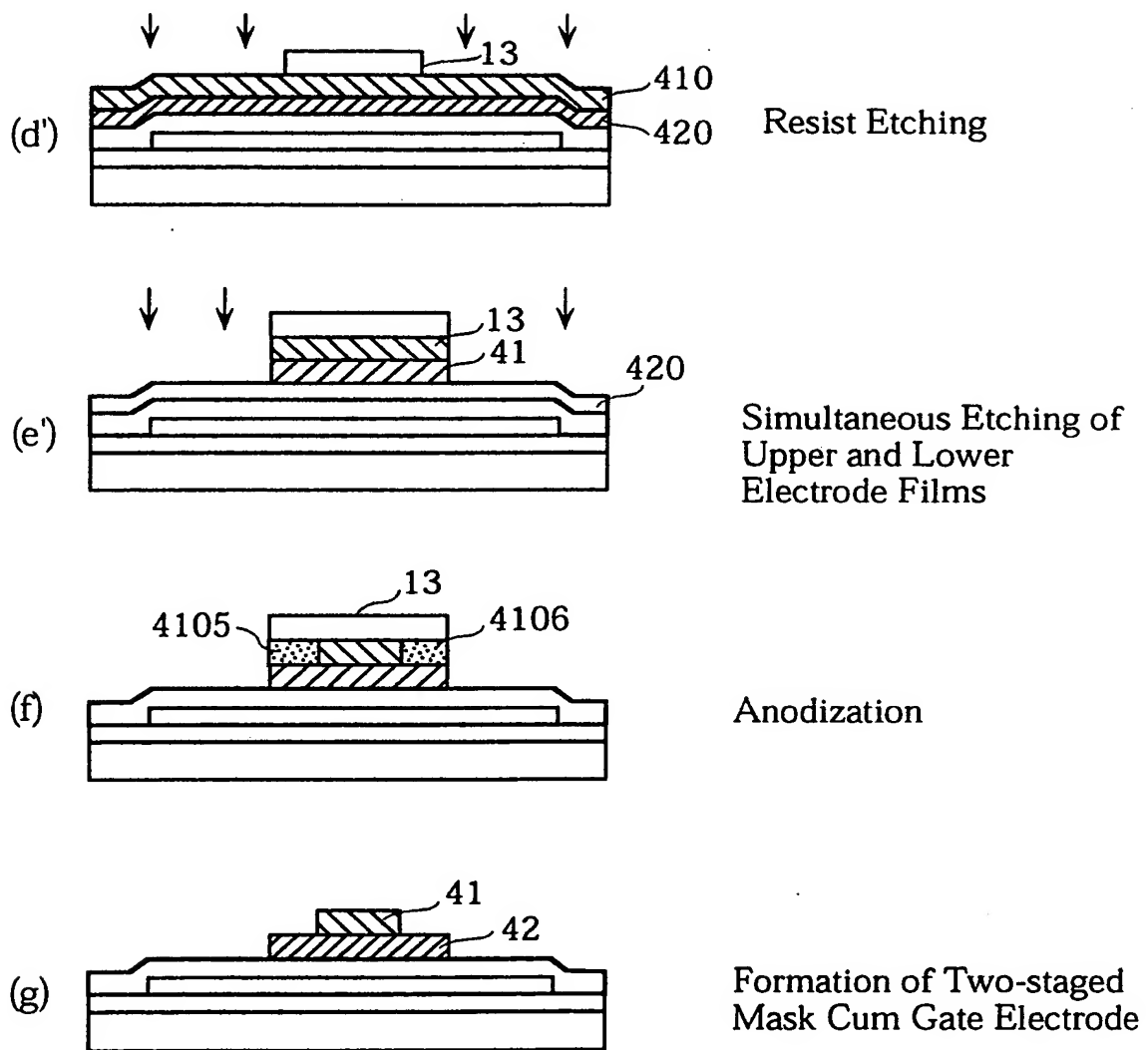


FIG. 25

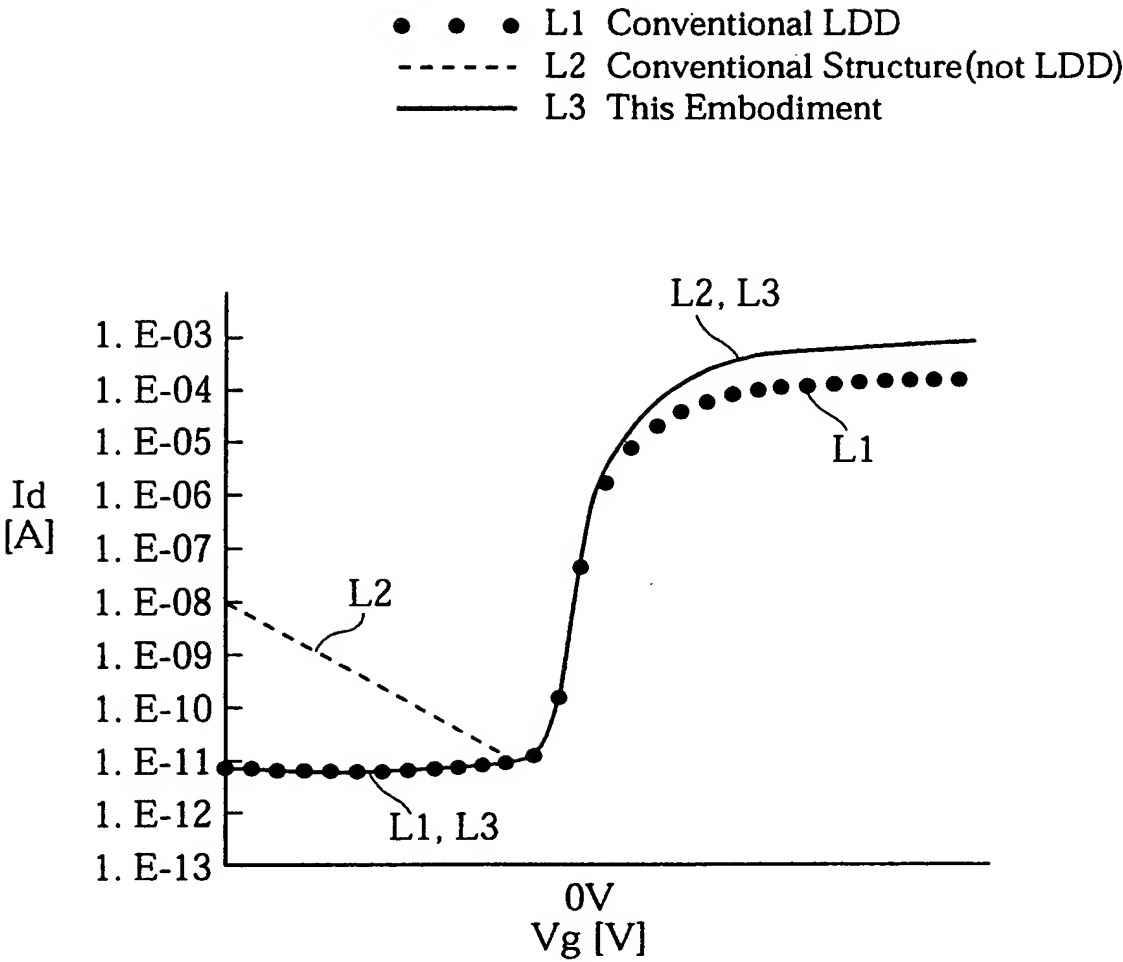


FIG. 26

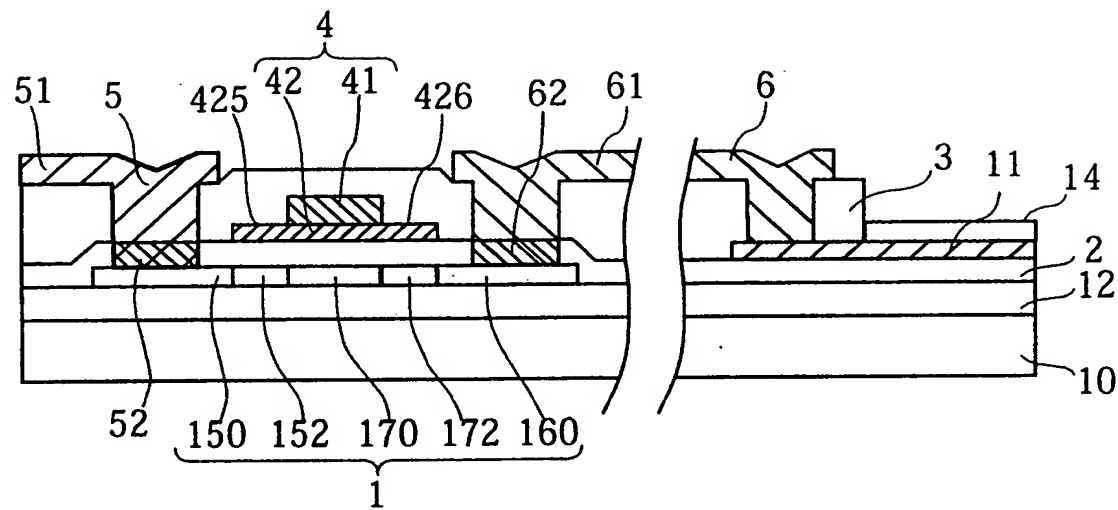


FIG. 27

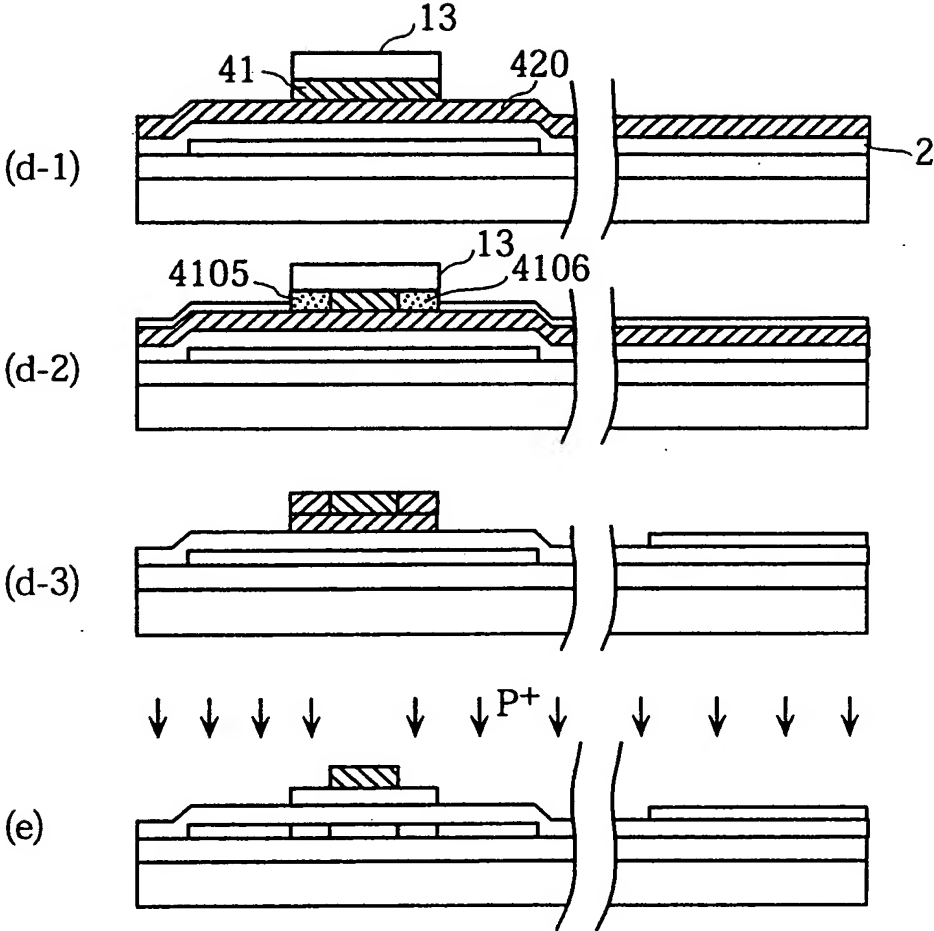


FIG. 28

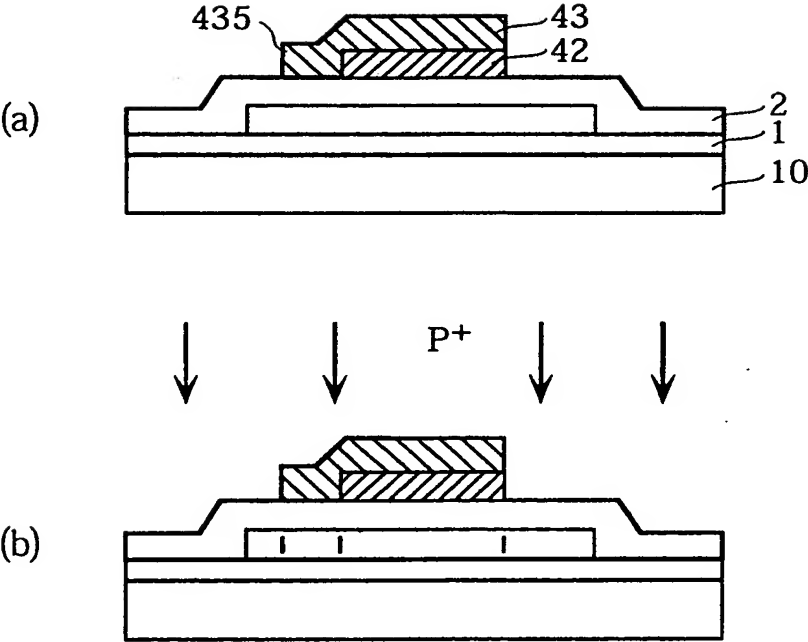


FIG. 29

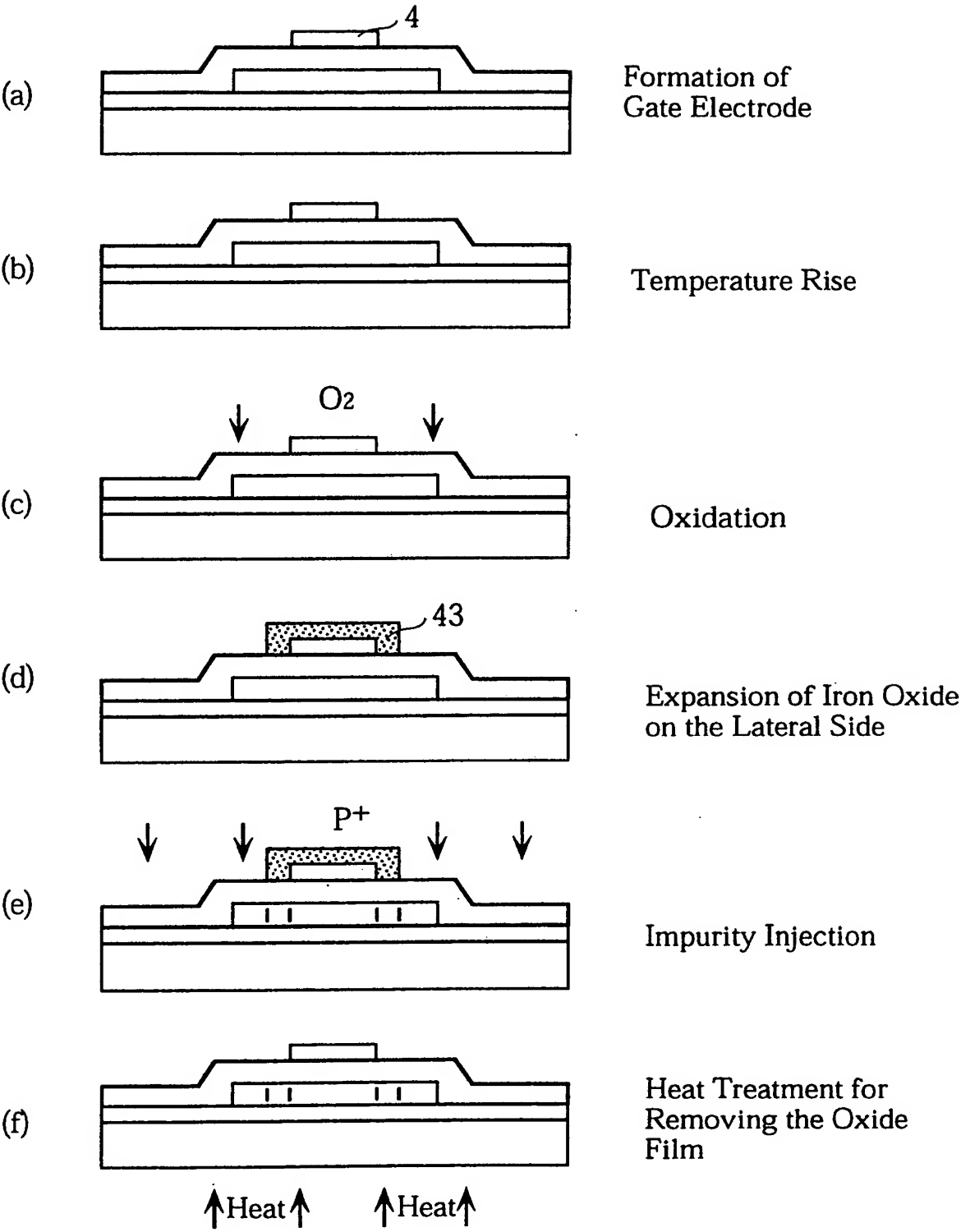


FIG. 30

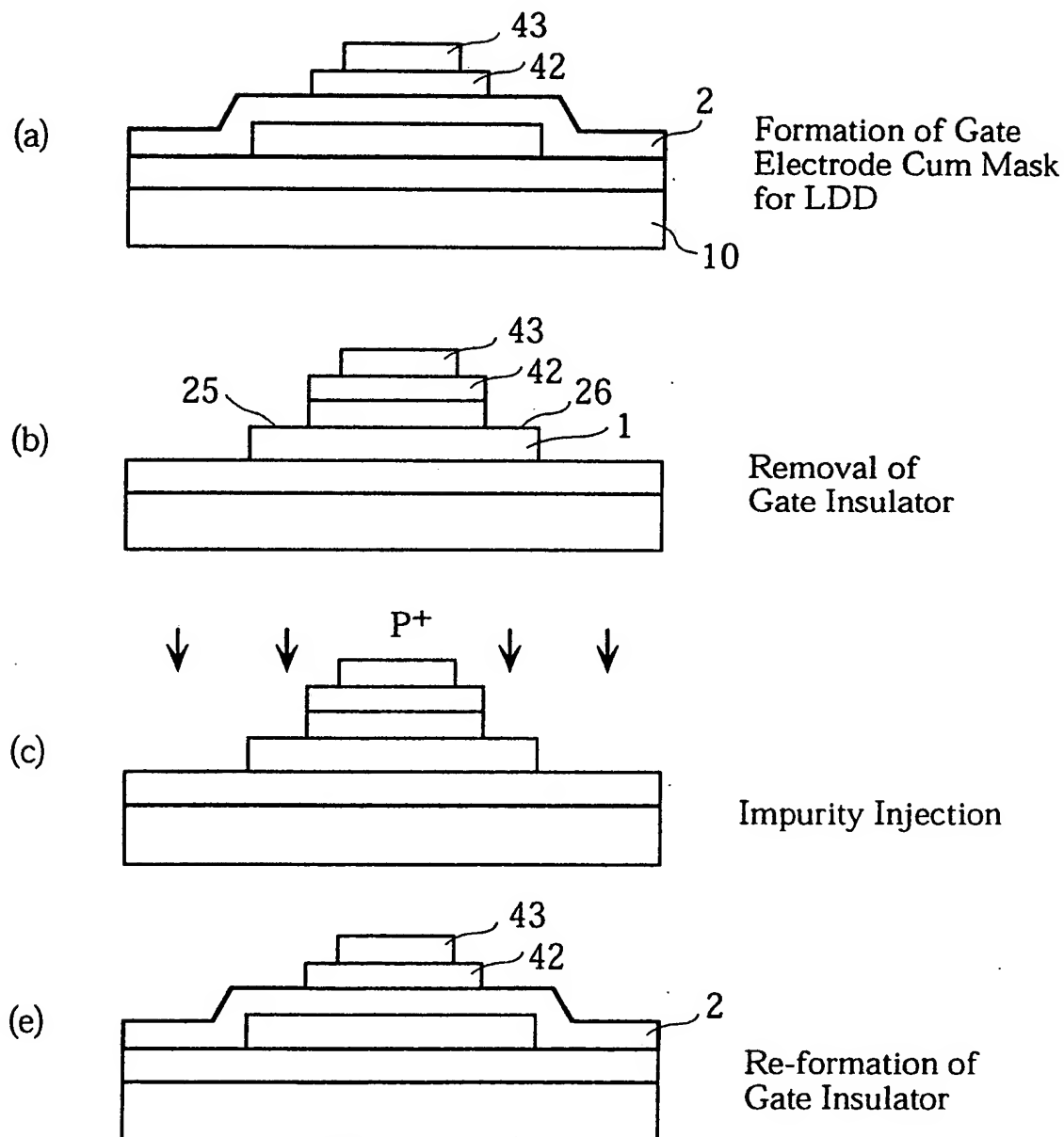


FIG. 31

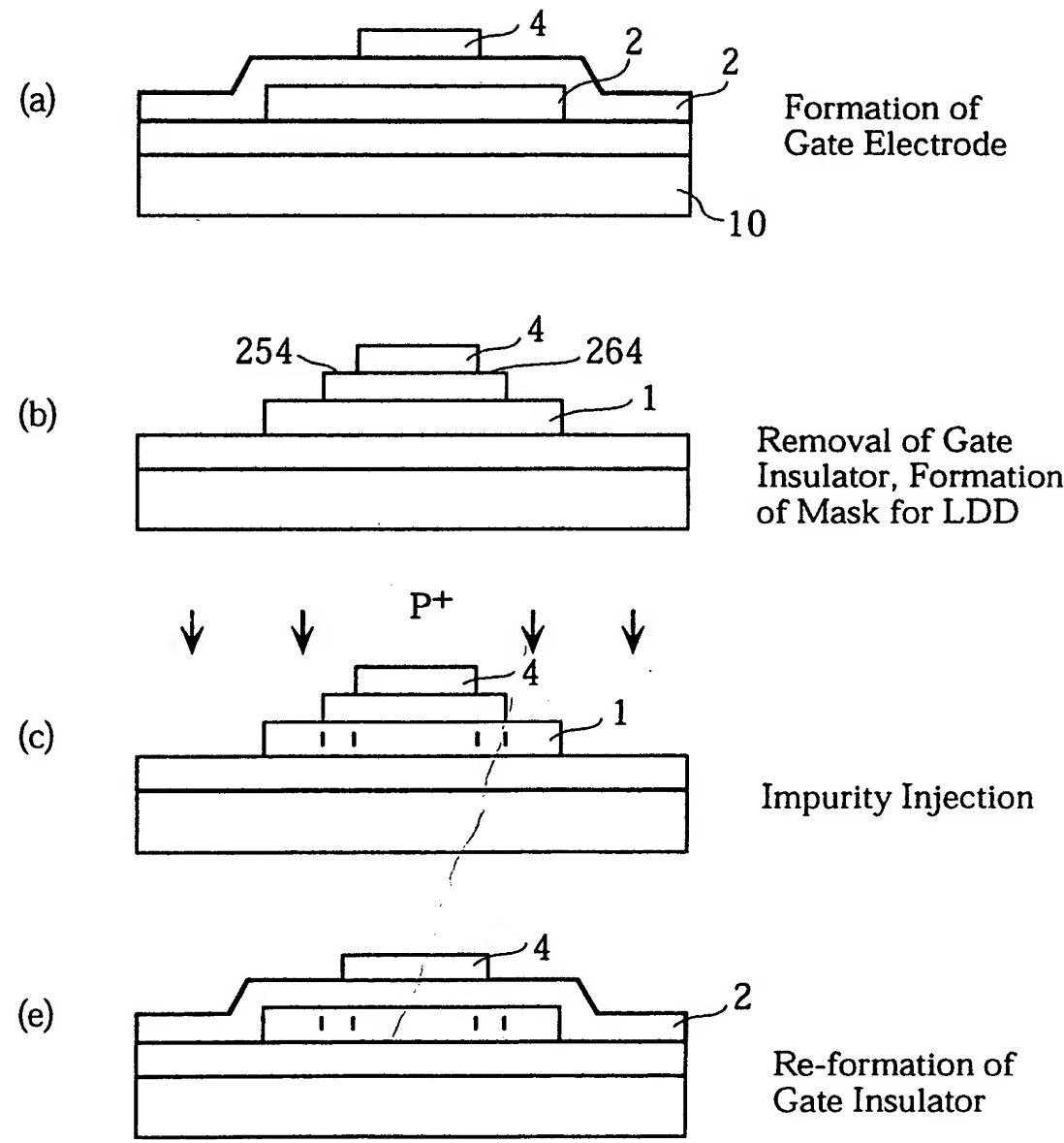
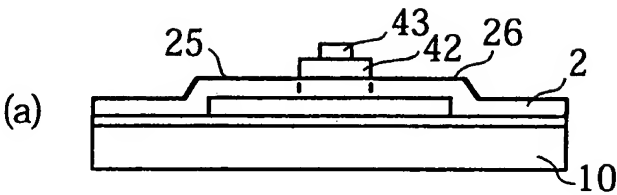
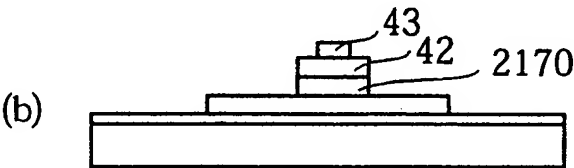


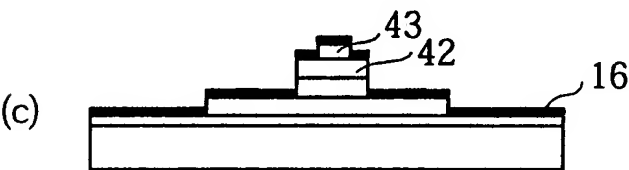
FIG. 32



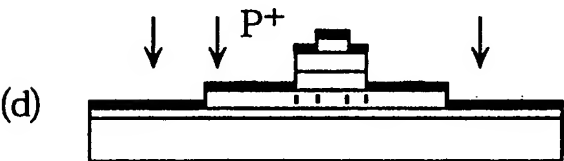
Formation of Gate
Electrode for LDD



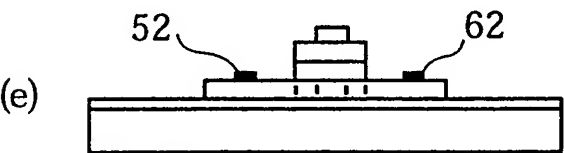
Removal of Gate Insulator



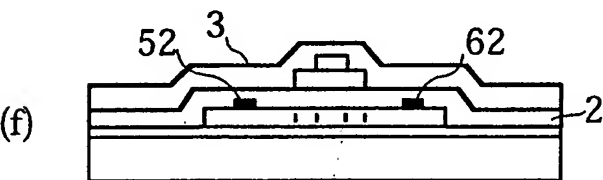
Formation of Ti Film



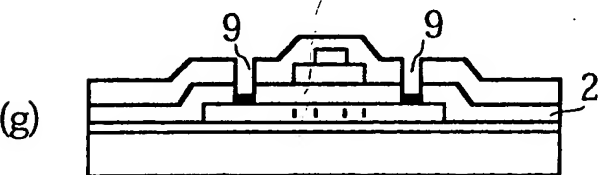
Impurity Injection



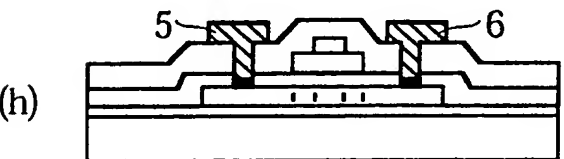
Removal of Ti Film



Re-formation of Gate Insulator,
Formation of Interlayer
Dielectric



Opening the Contact Hole



Aluminum Filling

FIG. 33

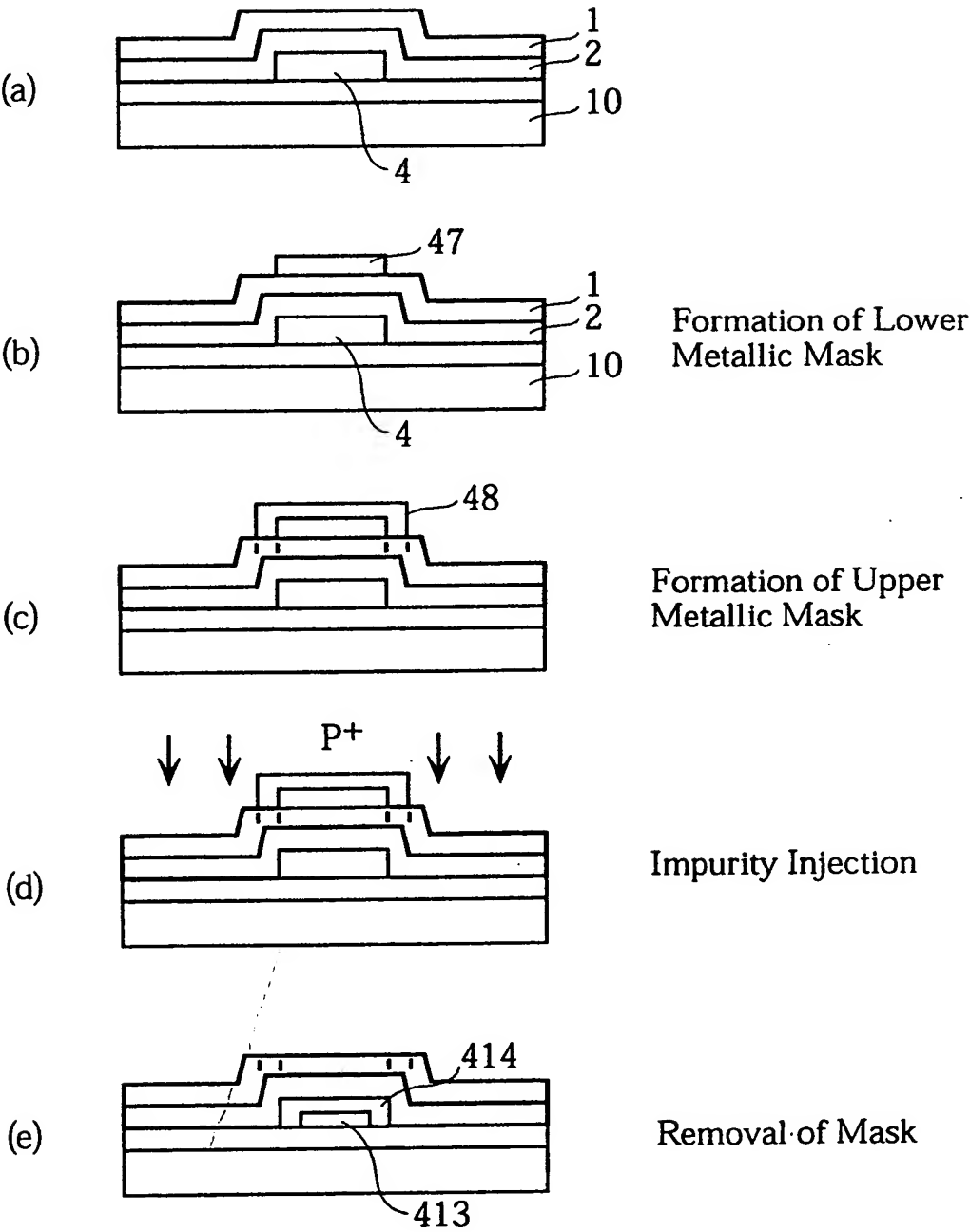


FIG. 34

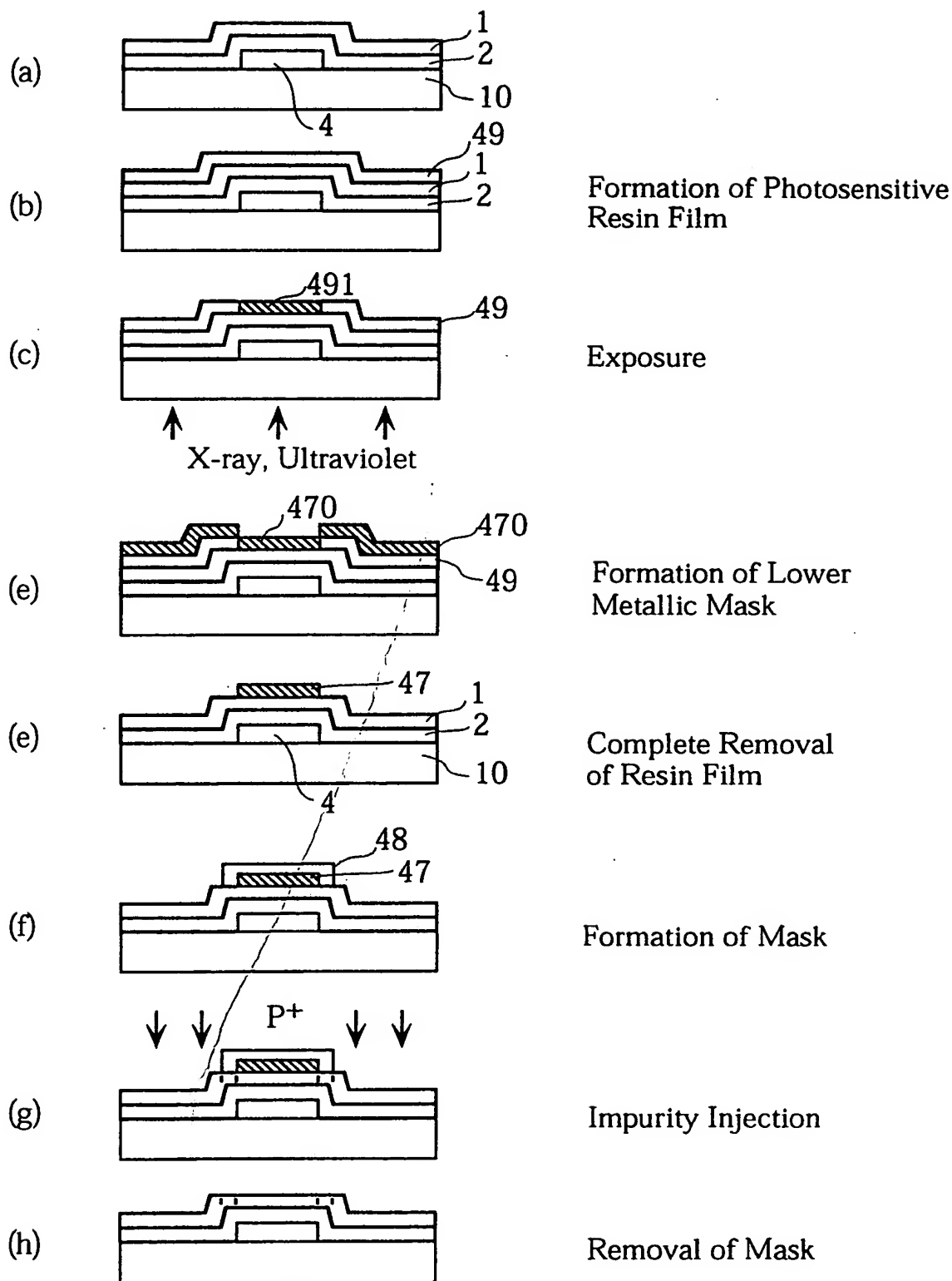


FIG. 35

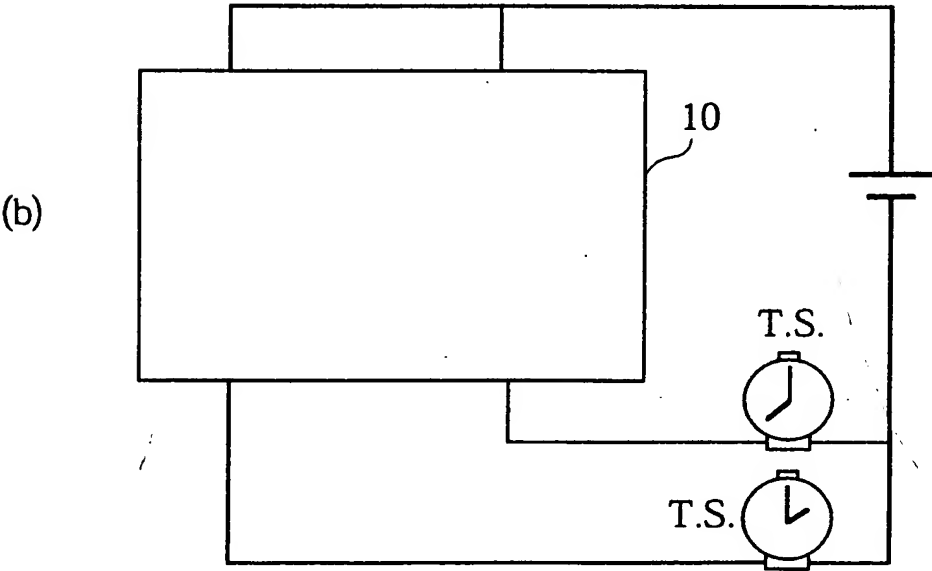
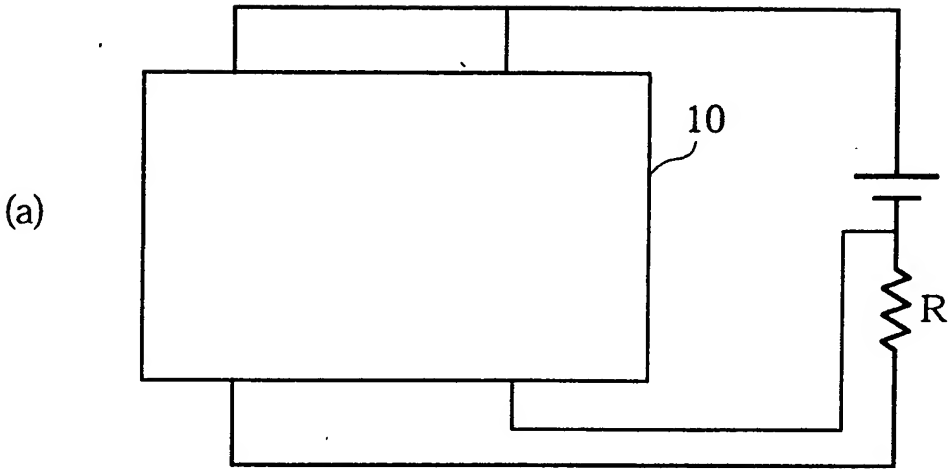


FIG. 36

